



3D Information Technologies for Tangible and Intangible Cultural Heritage

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Message from the Guest Editors

This Special Issue of *Applied Sciences*, entitled “3D Information Technologies for Tangible and Intangible Cultural Heritage”, will present the most recent advances and developments in the use of digital 3D technologies for the preservation of cultural heritage, both tangible and intangible. All interested authors are invited to submit high-quality papers for possible publication in this Special Issue that highlight the use of 3D digital technology to record, document, research and protect cultural heritage, as well as those focused on making such documentation available online.

All papers must present original, previously unpublished work and will be subject to the normal standards and peer-review process of this journal. Potential topics include but are not limited to:

- 3D scanning of objects and other elements (e.g. dances, performances and folk customs) of cultural heritage, both tangible and intangible;
- 3D information technologies for research of cultural heritage;
- Virtual and augmented reality technologies in cultural heritage research, presentation and dissemination.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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